

IC149 Series (SMT)

QFP/TQFP - 176 Pins (44x44) 0.5mm pitch

Specifications

Insulation Resistance:	500MΩ at 150V DC
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
Contact Resistance:	30mΩ max. at 10mA and 20mV
Operating Temp. Range:	-25°C to +85°C
Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
Contact: Beryllium Copper (BeCu)
Plating: Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5

Part Number (for IC-use)

IC149 - 176 - *66 - B5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

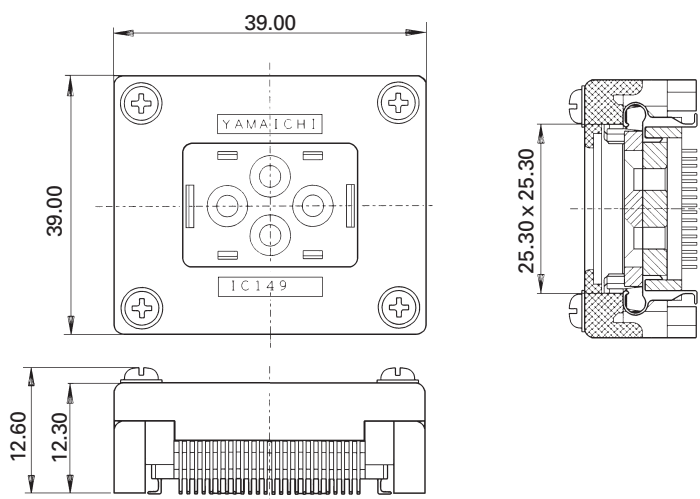
1 = With Pins

Contact Plating:

B5 = Au over Ni

Compatible Emulation-Adapter
not available

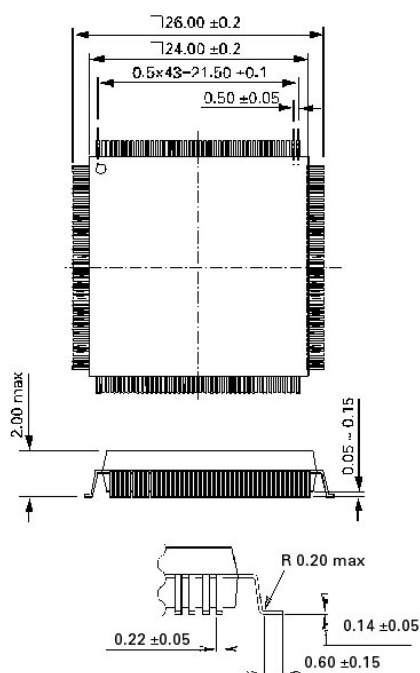
Outline Socket Dimensions (Reference Only)



Remarks

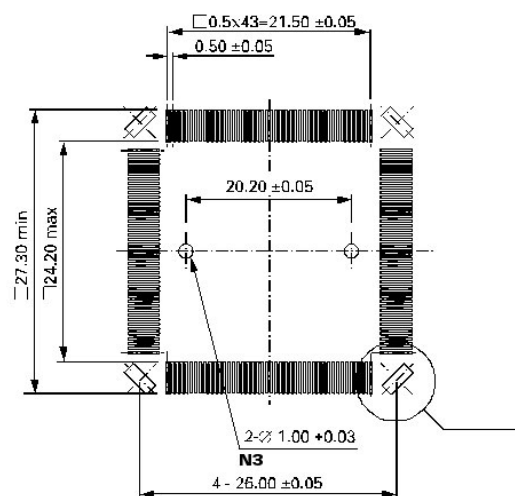
1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

IC - Dimensions



SocketPCB-Layout

Top View from Socket



Notes

- N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.
N3: These holes are only necessary for use with positioning pins.

IC149 Series (SMT)

QFP/TQFP - 272 Pins (68x68) 0.5mm pitch

Specifications

Insulation Resistance:	500MΩ at 150V DC
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
Contact Resistance:	30mΩ max. at 10mA and 20mV
Operating Temp. Range:	-25°C to +85°C
Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0

Contact: Beryllium Copper (BeCu)

Plating: Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5



Part Number (for IC-use)

IC149 - 272 - *29 - BB5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

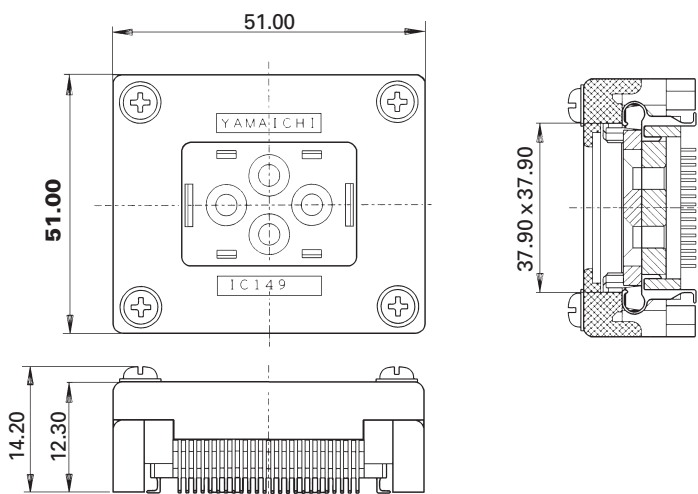
1 = With Pins

Contact Plating:

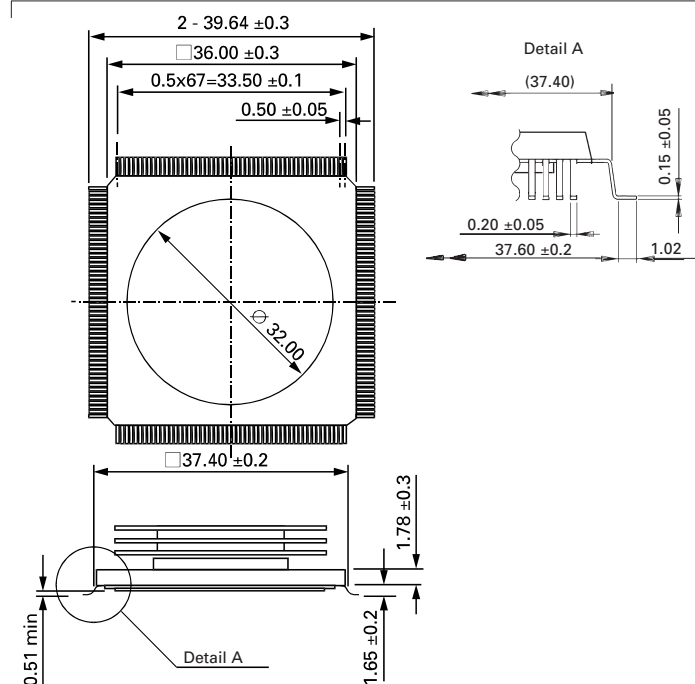
B5 = Au over Ni

Compatible Emulation-Adapter
not available

Outline Socket Dimensions (Reference Only)



IC - Dimensions



Notes

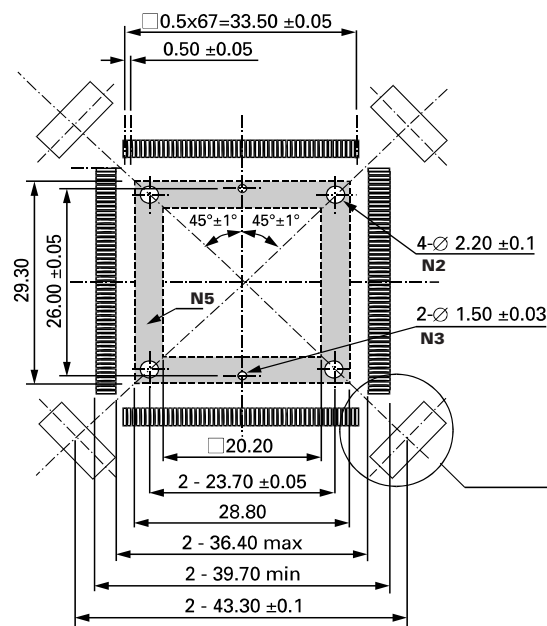
- N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.
- N2: These holes are only necessary when fixing the Socket with screws.
- N3: These holes are only necessary for use with positioning pins.
- N5: No conduits within this hatched area.

Remarks

1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

Socket PCB-Layout

Top View from Socket



IC149 Series (SMT)

QFP/TQFP - 208 Pins (52x52) 0.5mm pitch

Specifications

Insulation Resistance:	500MΩ at 150V DC
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
Contact Resistance:	30mΩ max. at 10mA and 20mV
Operating Temp. Range:	-25°C to +85°C
Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
Contact: Beryllium Copper (BeCu)
Plating: Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5



Part Number (for IC-use)

IC149 - 208 - *61 - B5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

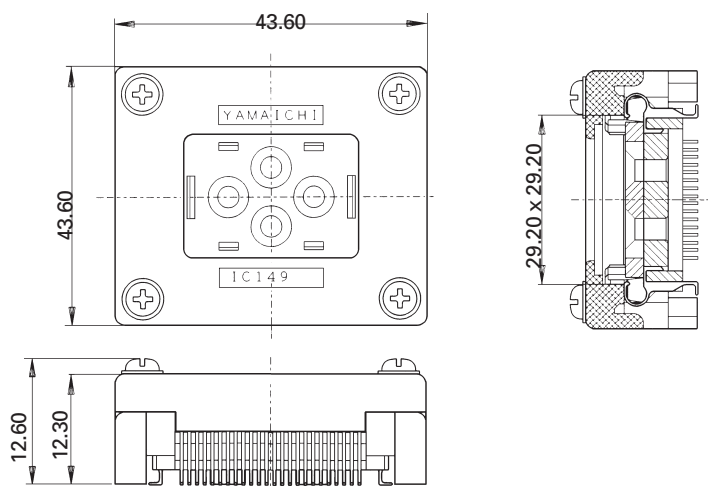
1 = With Pins

Contact Plating:

B5 = Au over Ni

Compatible Emulation-Adapter
not available

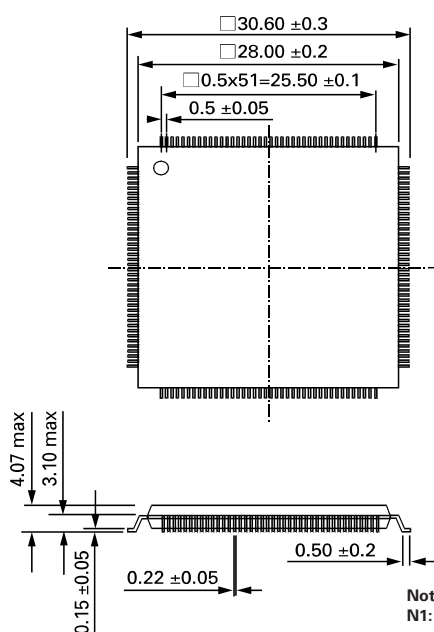
Outline Socket Dimensions (Reference Only)



Remarks

1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

IC - Dimensions



Notes:

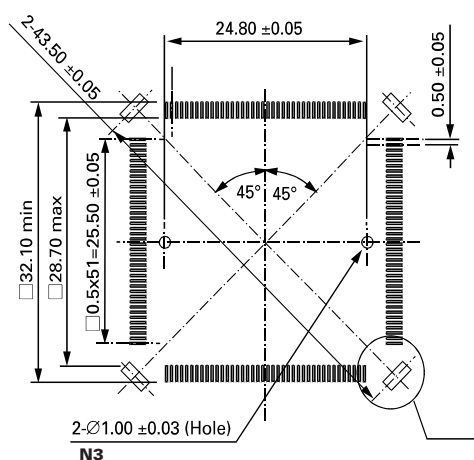
N1: Metal soldering Tab Clip.

Socket may be stabilized by soldering (Reflow) in these 4 areas.

N3: These holes are only necessary for use with positioning pins.

Socket PCB-Layout

Top View from Socket



Mouser Electronics

Authorized Distributor

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[IC149-176-066-B5](#) [IC149-208-061-B5](#)